

Excellent Integrated System Limited

Stocking Distributor

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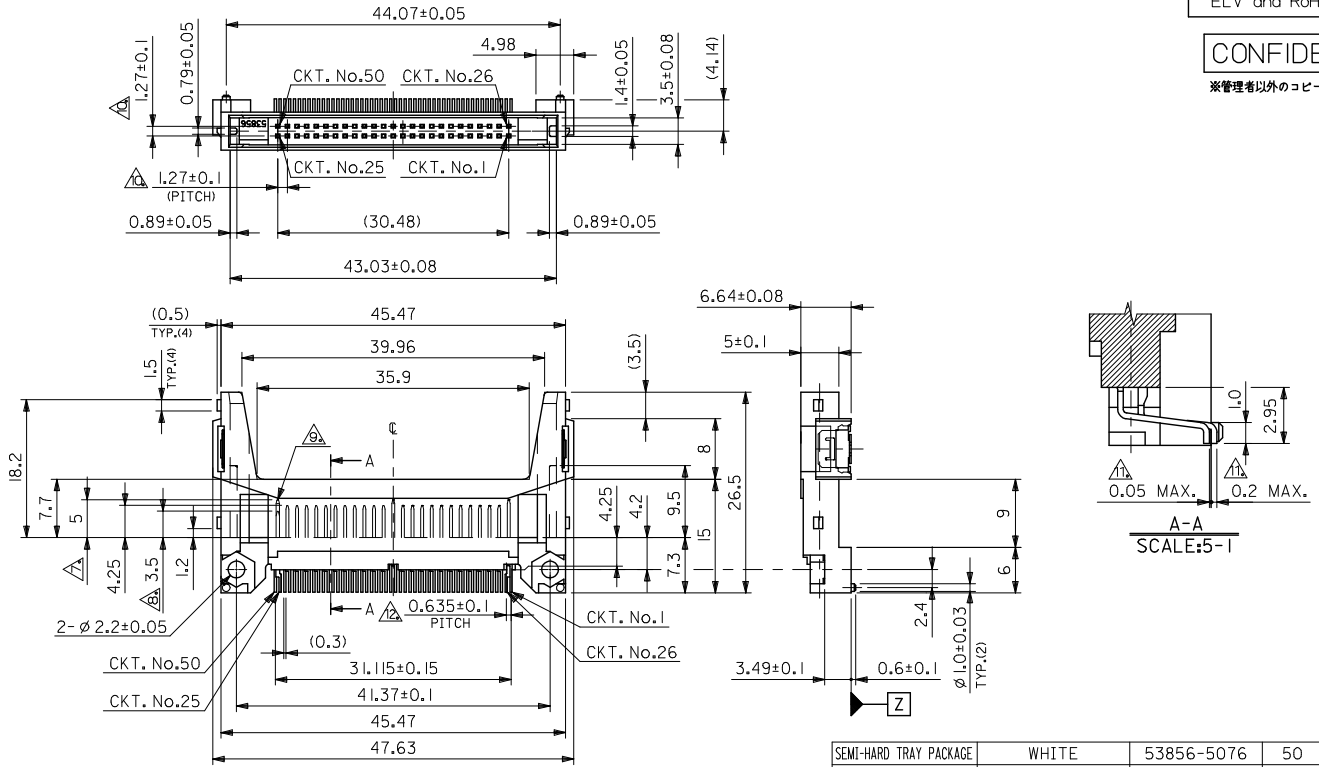
[Molex Connector Corporation](#)
[0538565070](#)

For any questions, you can email us directly:
sales@integrated-circuit.com

ELV and RoHS Compliant

CONFIDENTIAL

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SEMI-HARD TRAY PACKAGE	WHITE	53856-5076	50	53856-507*
SOFT TRAY PACKAGE	BLACK	53856-5071	50	
	WHITE	53856-5070	50	
PACKING TRAY FORM	HOUSING COLOR	MATERIAL No.	No. of Ckt.	MODEL No.

REVISED EC NO. J2015-1214 DRAWN/MATANABE01 2015/03/11 CHKD-AMI ZUMURA 2015/03/17 APPR-MYAGI 2015/03/23 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	MM ONLY		---	METRIC	☉ □
	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY DATE		TITLE		
	0.5 OVER	1.0 UNDER	±0.1	M.NABEI '04/03/16		CF CARD CONN. HEADER ASS'Y -LEAD FREE-		
	1.0 OVER	10 UNDER	±0.2	CHECKED BY DATE		molex		
10 OVER	30 UNDER	±0.25	K.TOJO '04/03/16		DOCUMENT NO.			
30 OVER		±0.3	APPROVED BY DATE		SD-53856-007			
ANGULAR ±3°			MATERIAL NO.		SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE CHART		1 OF 2			
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

注) NOTES

1. 材質
MATERIAL
ハウジング: ガラス入り LCP UL94V-0
HOUSING: LCP G.F. UL94V-0
ピン : リン青銅
PIN: PHOSPHOR BRONZE
ネール : リン青銅
NAIL: PHOSPHOR BRONZE
2. メッキ仕様
PLATING
PIN 接点部 : ニッケル下地、パラジウムニッケル、金メッキ
CONTACT AREA: PALLADIUM-NICKEL, GOLD OVER NICKEL
半田付け部 : 錫メッキ
SOLDER TAIL AREA: TIN
下地メッキ : ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL
NAIL 錫メッキ
TIN
下地メッキ : ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL

3. 推奨基板厚 : t 0.8 MIN.
RECOMMENDED P.C.B. THICKNESS: t 0.8 MIN.

4. 適合カード厚
RECOMMENDED CARD THICKNESS

接続部 : 3.3±0.1
CONNECTING AREA: 3.3±0.1

5. 適合カード幅 : 42.8±0.1
RECOMMENDED CARD WIDTH: 42.8±0.1

6. ハウジング色:
HOUSING COLOR:
53856-5010: 白 (WHITE)
53856-5010: 黒 (BLACK)

△寸 1,13,38,50
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS
1,13,38 AND 50.

△寸 25,26
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.

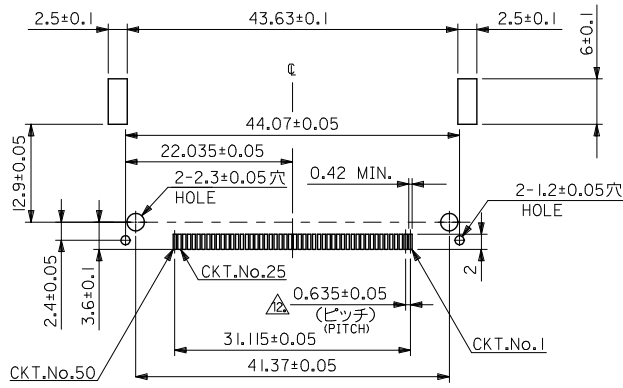
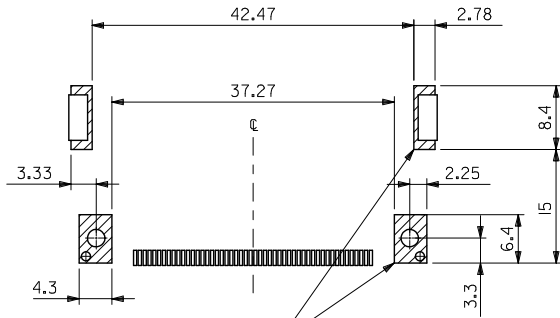
△ピンの倒れは、ピン根元を基準に全方向へ 0.1 MAX. とする。
PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1
WHEN MEASURED FROM PIN BASE.

△ピン根元に適用する。
THIS DIMENSION TO BE MEASURED AT PIN BASE.

△ソルダーテールは、Z面を基準とし上へ 0.05 下へ 0.2 の範囲にあり、
目ツソルダーテールの平坦度は、0.15 MAX. とし、テール先端にて測定する。
SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND
0.2 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY
OF SOLDER TAILS TO BE WITHIN 0.15.
MEASUREMENT POINT IS SOLDER TAILS TIP.

△公差非累積
NON-CUMULATIVE

13. 本製品は 53856-501* の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53856-501*.



基板推奨寸法
RECOMMENDED P.C.B. LAYOUT

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REVISED EC NO. J2015-1214 DRAWN/MATANABE01 2015/03/20 CHKD:AMI ZUMURA 2015/03/20 APPR:MYAGI 2015/03/23	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	M. NABEI	'04/03/16	CF CARD CONN. HEADER ASS'Y -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex		
	1.0 OVER	10 UNDER	±0.2	K. TOJO	'04/03/16	DOCUMENT NO. SD-53856-007		
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SHEET NO. 2 OF 2			
30 OVER		±0.3	M. SASAO	'04/03/16	SEE SHEET 1			
ANGULAR	±3 °		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE					

9 8 7 6 5 4 3 2 1